

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD40DP06NM	**Issued**	08. April 2022
MA#	MA005710374		
Package	PG-TO252-3-313	**Weight***	316.81 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.562	0.18	0.18	1773	1773
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		465	
	non noble metal	copper	7440-50-8	147.096	46.42	46.48	464298	464902
wire	non noble metal	aluminium	7429-90-5	0.690	0.22	0.22	2177	2177
encapsulation	inorganic material	zincoxide	1314-13-2	1.430	0.45		4515	
	miscellaneous	miscellaneous	-	7.152	2.26		22575	
	plastics	epoxy resin	-	21.456	6.77		67725	
	inorganic material	silicondioxide	60676-86-0	113.002	35.67	45.15	356683	451498
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11805	11805
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4484	4495
solder	non noble metal	tin	7440-31-5	0.017	0.01		55	
	noble metal	silver	7440-22-4	0.022	0.01		68	
	non noble metal	lead	7439-92-1	0.829	0.26	0.28	2616	2739
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60532	60611
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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